

IN THE CLAIMS:

No claims have been amended herein. All of the pending claims 1 through 3 are presented below. This listing of claims will replace all prior versions and listings of claims in the application.

Listing of Claims:

1. (Previously Presented) A semiconductor assembly comprising:
a substrate having a plurality of circuits on a portion of a surface thereof;
a semiconductor die having a plurality of bond pads located on an active surface thereof and
having a back side surface;
a plurality of solder balls connecting at least a portion of the plurality of bond pads of the
semiconductor die to at least a portion of the plurality of circuits of the substrate;
one of a glob top material and a low viscosity polymeric material filling any space between the
substrate and the semiconductor die;
a gel elastomer contacting at least a portion of the back side surface of the semiconductor die,
wherein the gel elastomer is compliant, adhesive, and filled with a thermally conductive
material; and
a heat sink cap having a portion thereof contacting a portion of the substrate covering the gel
elastomer, the semiconductor die, the plurality of solder balls, and a portion of the
substrate, the heat sink cap contacting at least a portion of the gel elastomer.
2. (Original) The semiconductor assembly of claim 1, wherein the heat sink cap
includes a plurality of fins thereon.
3. (Original) The semiconductor assembly of claim 1, wherein the gel elastomer
includes a cross-linked silicone.
4. (Previously Presented) A semiconductor assembly comprising:

a substrate having a surface having a plurality of circuits on a portion thereof;
a semiconductor die having a plurality of bond pads located on a first portion of an active surface thereof and having a back side surface;
a plurality of solder balls connecting at least a portion of the plurality of bond pads of the semiconductor die to at least a portion of the plurality of circuits of the substrate;
one of a glob top material and a low viscosity polymeric material filling any space between the substrate and the semiconductor die;
a gel elastomer contacting a portion of the back side surface of the semiconductor die, wherein the gel elastomer is a cross-linked silicone gel, compliant, adhesive, and filled with a thermally conductive material; and
a heat sink cap having a portion thereof in contact with a portion of the substrate and a portion of the gel elastomer, the heat sink cap covering the gel elastomer, the semiconductor die, the plurality of solder balls, and at least a portion of the substrate.

5. (Original) The semiconductor assembly of claim 4, wherein the heat sink cap includes a plurality of fins thereon.

6. (Previously Presented) An assembly comprising:
a substrate having a plurality of circuits on a portion thereof;
a semiconductor die having a plurality of bond pads located thereon and having a back side surface;
a plurality of solder balls connecting at least a portion of the plurality of bond pads of the semiconductor die to at least a portion of the plurality of circuits of the substrate;
one of a glob top material and a low viscosity polymeric material filling any space between the substrate and the semiconductor die;
a compliant, adhesive, and filled with a thermally conductive material, gel elastomer contacting at least a portion of the back side surface of the semiconductor die; and
a heat sink cap having a portion contacting a portion of the substrate covering the compliant, adhesive, and filled with a thermally conductive material, gel elastomer, the

semiconductor die, the plurality of solder balls, and a portion of the substrate, the heat sink cap contacting at least a portion of the gel elastomer.

7. (Original) The semiconductor assembly of claim 6, wherein the heat sink cap includes a plurality of fins thereon.

8. (Previously Presented) The semiconductor assembly of claim 6, wherein the compliant, adhesive, and filled with a thermally conductive material, gel elastomer includes a cross-linked silicone.

9. (Previously Presented) An assembly comprising:
a substrate having a plurality of circuits on a portion thereof;
a semiconductor die having a plurality of bond pads and having a back side surface;
a plurality of solder balls connecting at least a portion of the plurality of bond pads of the semiconductor die to at least a portion of the plurality of circuits of the substrate;
one of a glob top material and a low viscosity polymeric material filling any space between the substrate and the semiconductor die;
a compliant, adhesive, and filled with a thermally conductive material, gel elastomer contacting a portion of the back side surface of the semiconductor die, and
a heat sink cap having a portion thereof in contact with a portion of the substrate and a portion of the compliant, adhesive, and filled with a thermally conductive material, gel elastomer, the heat sink cap covering the compliant, adhesive, and filled with a thermally conductive material, gel elastomer, the semiconductor die, the plurality of solder balls, and at least a portion of the substrate.

10. (Original) The semiconductor assembly of claim 9, wherein the heat sink cap includes a plurality of fins thereon.